



PC Board Layout  
Component Side Shown

NOTES:

MATERIAL :

- 1.HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
- 2.CONTACT MATERIAL :PHOSPHOR BRONZE φ0.46mm.
- 3.PLATING :GOLD PLATING OVER NICKEL.

ELECTRICAL:

- 1.VOLTAGE RATING :125 VAC RMS.
- 2.CURRENT RATING :1.5 AMP.
- 3.CONTACT RESISTANCE :30 MILLIOHMS MAX.
- 4.INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC .
- 5.DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

- 1.DURRABILITY :750 CYCLES MIN.
- 2.PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

- 1. STORAGE : -40°C~+85°C
- 2. OPERATION : 0°C TO 70°C.

← MM INCH →		DFTO SHB	DATE 2007.05.03	<h1 style="margin: 0;">Coor le库乐科技</h1>	
TOLERANCES EXCEPT AS NOTED		CHKD LANBO	DATE 2007.05.03		
DETACHED LISTS	MM	MFO	DATE	TITLE <h2 style="margin: 0;">56 1x1 8P8C</h2>	
	.0 ± 0.15	APPVL	DATE		
	.00 ± 0.075	MATERIAL :		DRAWING NO. _____ SIZE /PART NO. _____ A3	
	.000 ± 0.05	MATERIAL :			
ANGLES ± 0.5		QTY :		DO NOT SCALE DRAWING	
		FINISH :			
THIRD ANGLE PROJECTION		SCALE :			